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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	5184
Number of Logic Elements/Cells	51840
Total RAM Bits	442368
Number of I/O	488
Number of Gates	2392000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	652-BBGA
Supplier Device Package	652-BGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k1500cb652c8es

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Register a1 LUT b1 Carry Chain LE1 a2 Register ► s2 LUT b2 Carry Chain LE2 Register LUT an b*n* Carry Chain LE*n* Register ➤ Carry-Out LUT Carry Chain LE*n* + 1

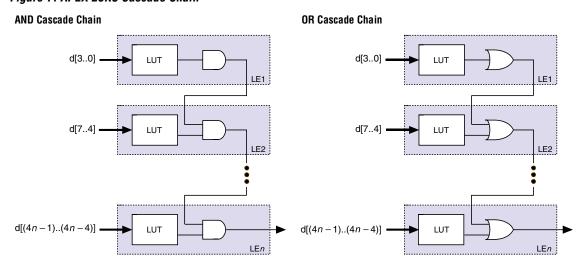
Figure 6. APEX 20KC Carry Chain

Cascade Chain

With the cascade chain, the APEX 20KC architecture can implement functions with a very wide fan-in. Adjacent LUTs can compute portions of a function in parallel; the cascade chain serially connects the intermediate values. The cascade chain can use a logical AND or logical OR (via De Morgan's inversion) to connect the outputs of adjacent LEs. Each additional LE provides four more inputs to the effective width of a function, with a short cascade delay. Cascade chain logic can be created automatically by the Quartus II Compiler during design processing, or manually by the designer during design entry.

Cascade chains longer than ten LEs are implemented automatically by linking LABs together. For enhanced fitting, a long cascade chain skips alternate LABs in a MegaLAB structure. A cascade chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure. Figure 7 shows how the cascade function can connect adjacent LEs to form functions with a wide fan-in.

Figure 7. APEX 20KC Cascade Chain



Normal Mode

The normal mode is suitable for general logic applications, combinatorial functions, or wide decoding functions that can take advantage of a cascade chain. In normal mode, four data inputs from the LAB local interconnect and the carry-in are inputs to a four-input LUT. The Quartus II Compiler automatically selects the carry-in or the DATA3 signal as one of the inputs to the LUT. The LUT output can be combined with the cascade-in signal to form a cascade chain through the cascade-out signal. LEs in normal mode support packed registers.

Arithmetic Mode

The arithmetic mode is ideal for implementing adders, accumulators, and comparators. An LE in arithmetic mode uses two 3-input LUTs. One LUT computes a three-input function; the other generates a carry output. As shown in Figure 8, the first LUT uses the carry-in signal and two data inputs from the LAB local interconnect to generate a combinatorial or registered output. For example, when implementing an adder, this output is the sum of three signals: DATA1, DATA2, and carry-in. The second LUT uses the same three signals to generate a carry-out signal, thereby creating a carry chain. The arithmetic mode also supports simultaneous use of the cascade chain. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

The Quartus II software implements parameterized functions that use the arithmetic mode automatically where appropriate; the designer does not need to specify how the carry chain will be used.

Counter Mode

The counter mode offers clock enable, counter enable, synchronous up/down control, synchronous clear, and synchronous load options. The counter enable and synchronous up/down control signals are generated from the data inputs of the LAB local interconnect. The synchronous clear and synchronous load options are LAB-wide signals that affect all registers in the LAB. Consequently, if any of the LEs in an LAB use the counter mode, other LEs in that LAB must be used as part of the same counter or be used for a combinatorial function. The Quartus II software automatically places any registers that are not used by the counter into other LABs.

The programmable register also supports an asynchronous clear function. Within the ESB, two asynchronous clears are generated from global signals and the local interconnect. Each macrocell can either choose between the two asynchronous clear signals or choose to not be cleared. Either of the two clear signals can be inverted within the ESB. Figure 15 shows the ESB control logic when implementing product-terms.

Dedicated Clocks Global Signals Local Interconnect Local Interconnect Local Interconnect Local Interconnect CLR1 CLK2 CLKENA2 CLK1 CLKENA1 CLR2

Figure 15. ESB Product-Term Mode Control Logic

Parallel Expanders

Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 32 product terms to feed the macrocell OR logic directly, with two product terms provided by the macrocell and 30 parallel expanders provided by the neighboring macrocells in the ESB.

The Quartus II Compiler can allocate up to 15 sets of up to two parallel expanders per set to the macrocells automatically. Each set of two parallel expanders incurs a small, incremental timing delay. Figure 16 shows the APEX 20KC parallel expanders.

Input/Output Clock Mode

The input/output clock mode contains two clocks. One clock controls all registers for inputs into the ESB: data input, WE, RE, read address, and write address. The other clock controls the ESB data output registers. The ESB also supports clock enable and asynchronous clear signals; these signals also control the reading and writing of registers independently. Input/output clock mode is commonly used for applications where the reads and writes occur at the same system frequency, but require different clock enable signals for the input and output registers. Figure 21 shows the ESB in input/output clock mode.

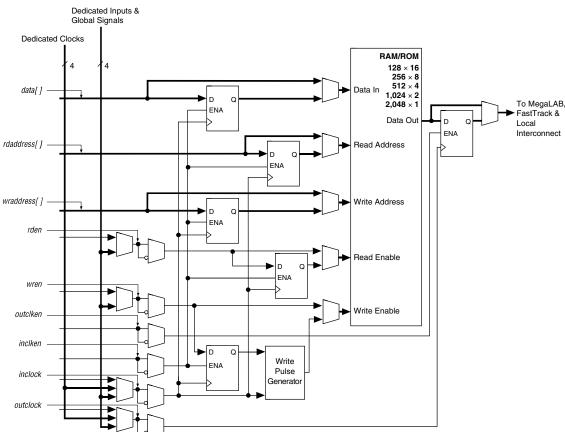


Figure 21. ESB in Input/Output Clock Mode Note (1)

Note:

(1) All registers can be cleared asynchronously by ESB local interconnect signals, global signals, or the chip-wide reset.

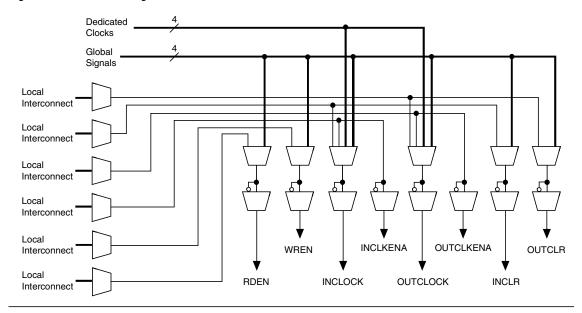


For more information on APEX 20KC devices and CAM, see *Application Note 119 (Implementing High-Speed Search Applications with APEX CAM)*.

Driving Signals to the ESB

ESBs provide flexible options for driving control signals. Different clocks can be used for the ESB inputs and outputs. Registers can be inserted independently on the data input, data output, read address, write address, WE, and RE signals. The global signals and the local interconnect can drive the WE and RE signals. The global signals, dedicated clock pins, and local interconnect can drive the ESB clock signals. Because the LEs drive the local interconnect, the LEs can control the WE and RE signals and the ESB clock, clock enable, and asynchronous clear signals. Figure 24 shows the ESB control signal generation logic.

Figure 24. ESB Control Signal Generation



An ESB is fed by the local interconnect, which is driven by adjacent LEs (for high-speed connection to the ESB) or the MegaLAB interconnect. The ESB can drive the local, MegaLAB, or FastTrack interconnect routing structure to drive LEs and IOEs in the same MegaLAB structure or anywhere in the device.

Implementing Logic in ROM

In addition to implementing logic with product terms, the ESB can implement logic functions when it is programmed with a read-only pattern during configuration, creating a large LUT. With LUTs, combinatorial functions are implemented by looking up the results, rather than by computing them. This implementation of combinatorial functions can be faster than using algorithms implemented in general logic, a performance advantage that is further enhanced by the fast access times of ESBs. The large capacity of ESBs enables designers to implement complex functions in one logic level without the routing delays associated with linked LEs or distributed RAM blocks. Parameterized functions such as LPM functions can take advantage of the ESB automatically. Further, the Quartus II software can implement portions of a design with ESBs where appropriate.

Programmable Speed/Power Control

APEX 20KC ESBs offer a high-speed mode that supports very fast operation on an ESB-by-ESB basis. When high speed is not required, this feature can be turned off to reduce the ESB's power dissipation by up to 50%. ESBs that run at low power incur a nominal timing delay adder. This Turbo BitTM option is available for ESBs that implement product-term logic or memory functions. An ESB that is not used will be powered down so that it does not consume DC current.

Designers can program each ESB in the APEX 20KC device for either high-speed or low-power operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths operate at reduced power.

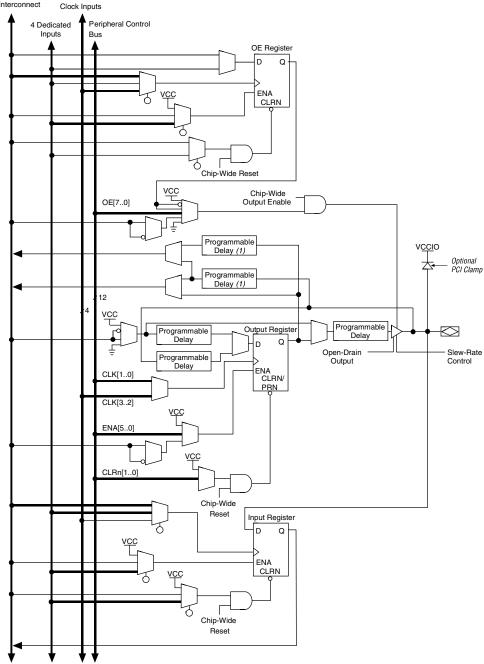
I/O Structure

The APEX 20KC IOE contains a bidirectional I/O buffer and a register that can be used either as an input register for external data requiring fast setup times or as an output register for data requiring fast clock-to-output performance. IOEs can be used as input, output, or bidirectional pins.

APEX 20KC devices include an enhanced IOE, which drives the FastRow interconnect. The FastRow interconnect connects a column I/O pin directly to the LAB local interconnect within two MegaLAB structures. This feature provides fast setup times for pins that drive high fan-outs with complex logic, such as PCI designs. For fast bidirectional I/O timing, LE registers using local routing can improve setup times and OE timing. The APEX 20KC IOE also includes direct support for open-drain operation, giving faster clock-to-output for open-drain signals. Some programmable delays in the APEX 20KC IOE offer multiple levels of delay to fine-tune setup and hold time requirements. The Quartus II Compiler sets these delays by default to minimize setup time while providing a zero hold time.

Figure 25. APEX 20KC Bidirectional I/O Registers Notes (1), (2)

Row, Column, FastRow, or Local Interconnect Clock Inputs



Notes:

- (1) This programmable delay has four settings: off and three levels of delay.
- (2) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

Table 26. 3.3-V PCI-X Specifications									
Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units			
V _{CCIO}	Output supply voltage		3.0	3.3	3.6	V			
V _{IH}	High-level input voltage		0.5 × V _{CCIO}		V _{CCIO} + 0.5	V			
V _{IL}	Low-level input voltage		-0.5		0.35 × V _{CCIO}	V			
V _{IPU}	Input pull-up voltage		0.7 × V _{CCIO}			V			
I _{IL}	Input pin leakage current	0 < V _{IN} < V _{CCIO}	-10.0		10.0	μΑ			
V _{OH}	High-level output voltage	I _{OUT} = -500 μA	0.9 × V _{CCIO}			V			
V _{OL}	Low-level output voltage	I _{OUT} = 1500 μA			0.1 × V _{CCIO}	V			
L _{pin}	Pin Inductance				15.0	nΗ			

Table 27. 3.3-V LVDS I/O Specifications										
Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units				
V _{CCIO}	I/O supply voltage		3.135	3.3	3.465	V				
V _{OD}	Differential output voltage	R _L = 100 Ω	250		450	mV				
ΔV _{OD}	Change in VOD between high and low	R _L = 100 Ω			50	mV				
V _{OS}	Output offset voltage	R _L = 100 Ω	1.125	1.25	1.375	V				
ΔV _{OS}	Change in VOS between high and low	R _L = 100 Ω			50	mV				
V _{TH}	Differential input threshold	V _{CM} = 1.2 V	-100		100	mV				
V _{IN}	Receiver input voltage range		0.0		2.4	V				
R _L	Receiver differential input resistor (external to APEX devices)		90	100	110	Ω				

Table 30. SSTL-2 Class II Specifications									
Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units			
V _{CCIO}	I/O supply voltage		2.375	2.5	2.625	V			
V _{TT}	Termination voltage		V _{REF} - 0.04	V _{REF}	V _{REF} + 0.04	V			
V_{REF}	Reference voltage		1.15	1.25	1.35	V			
V _{IH}	High-level input voltage		V _{REF} + 0.18		V _{CCIO} + 0.3	V			
V _{IL}	Low-level input voltage		-0.3		V _{REF} – 0.18	V			
V _{OH}	High-level output voltage	I _{OH} = -15.2 mA (1)	V _{TT} + 0.76			V			
V _{OL}	Low-level output voltage	I _{OL} = 15.2 mA (2)			V _{TT} – 0.76	V			

Table 31. SSTL-3 Class I Specifications									
Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units			
V _{CCIO}	I/O supply voltage		3.0	3.3	3.6	V			
V _{TT}	Termination voltage		V _{REF} – 0.05	V_{REF}	V _{REF} + 0.05	٧			
V_{REF}	Reference voltage		1.3	1.5	1.7	V			
V _{IH}	High-level input voltage		V _{REF} + 0.2		V _{CCIO} + 0.3	V			
V _{IL}	Low-level input voltage		-0.3		V _{REF} – 0.2	V			
V _{OH}	High-level output voltage	$I_{OH} = -8 \text{ mA } (1)$	V _{TT} + 0.6			V			
V _{OL}	Low-level output voltage	I _{OL} = 8 mA (2)			V _{TT} – 0.6	V			

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V _{CCIO}	I/O supply voltage		3.0	3.3	3.6	V
V _{TT}	Termination voltage		V _{REF} - 0.05	V _{REF}	V _{REF} + 0.05	V
V _{REF}	Reference voltage		1.3	1.5	1.7	V
V _{IH}	High-level input voltage		V _{REF} + 0.2		V _{CCIO} + 0.3	V
V _{IL}	Low-level input voltage		-0.3		V _{REF} - 0.2	V
V _{OH}	High-level output voltage	I _{OH} = -16 mA (1)	V _{TT} + 0.8			V
V _{OL}	Low-level output voltage	I _{OL} = 16 mA (2)			V _{TT} – 0.8	V

Table 33. HS	Table 33. HSTL Class I I/O Specifications										
Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units					
V _{CCIO}	I/O supply voltage		1.71	1.8	1.89	V					
V _{TT}	Termination voltage		V _{REF} – 0.05	V _{REF}	V _{REF} + 0.05	V					
V_{REF}	Reference voltage		0.68	0.75	0.90	V					
V _{IH}	High-level input voltage		V _{REF} + 0.1		V _{CCIO} + 0.3	V					
V _{IL}	Low-level input voltage		-0.3		V _{REF} – 0.1	V					
V _{OH}	High-level output voltage	I _{OH} = -8 mA (1)	V _{CCIO} - 0.4			V					
V _{OL}	Low-level output voltage	I _{OL} = 8 mA (2)			0.4	V					

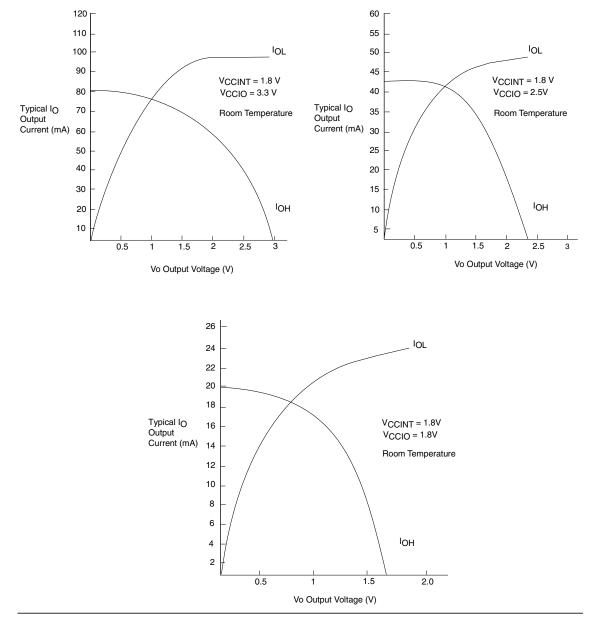


Figure 32. Output Drive Characteristics of APEX 20KC Devices

Timing Model

The high-performance FastTrack and MegaLAB interconnect routing resources ensure predictable performance, accurate simulation, and accurate timing analysis. This predictable performance contrasts with that of FPGAs, which use a segmented connection scheme and therefore have unpredictable performance.

Table 38. APEX 20	OKC f _{MAX} ESB Timing Parameters							
Symbol	Parameter							
t _{ESBARC}	ESB asynchronous read cycle time							
t _{ESBSRC}	ESB synchronous read cycle time							
t _{ESBAWC}	ESB asynchronous write cycle time							
t _{ESBSWC}	ESB synchronous write cycle time							
t _{ESBWASU}	ESB write address setup time with respect to WE							
t _{ESBWAH}	ESB write address hold time with respect to WE							
t _{ESBWDSU}	ESB data setup time with respect to WE							
t _{ESBWDH}	ESB data hold time with respect to WE							
t _{ESBRASU}	ESB read address setup time with respect to RE							
t _{ESBRAH}	ESB read address hold time with respect to RE							
t _{ESBWESU}	ESB WE setup time before clock when using input register							
t _{ESBDATASU}	ESB data setup time before clock when using input register							
t _{ESBWADDRSU}	ESB write address setup time before clock when using input registers							
t _{ESBRADDRSU}	ESB read address setup time before clock when using input registers							
t _{ESBDATACO1}	ESB clock-to-output delay when using output registers							
t _{ESBDATACO2}	ESB clock-to-output delay without output registers							
t _{ESBDD}	ESB data-in to data-out delay for RAM mode							
t _{PD}	ESB macrocell input to non-registered output							
t _{PTERMSU}	ESB macrocell register setup time before clock							
t _{PTERMCO}	ESB macrocell register clock-to-output delay							

Table 39. APEX 20KC f _{MAX} Routing Delays								
Symbol	Parameter							
t _{F1-4}	Fan-out delay estimate using local interconnect							
t _{F5-20}	Fan-out delay estimate using MegaLab interconnect							
t _{F20+}	Fan-out delay estimate using FastTrack interconnect							

Table 45. EP20K100C f _{MAX} Routing Delays Note (1)									
Symbol	-7 Speed Grade		-7 Speed Grade -8 Speed Grade (2)		-9 Speed Grade (2)		Unit		
	Min	Max	Min	Max	Min	Max			
t _{F1-4}	0.2						ns		
t _{F5-20}	0.9						ns		
t _{F20+}	1.0						ns		

Table 46. EP20K100C Minimum Pulse Width Timing Parameters Note (1)										
Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit			
	Min	Max	Min	Max	Min	Max				
t _{CH}	2.3						ns			
t_{CL}	2.3						ns			
t _{CLRP}	0.2						ns			
t _{PREP}	0.2						ns			
t _{ESBCH}	2.3						ns			
t _{ESBCL}	2.3						ns			
t _{ESBWP}	1.1						ns			
t _{ESBRP}	0.9						ns			

Table 47. EP20K100C External Timing Parameters										
Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit			
	Min	Max	Min	Max	Min	Max				
t _{INSU}	2.0						ns			
t _{INH}	0.0						ns			
tоитсо	2.0	5.0					ns			
t _{INSUPLL}	3.3						ns			
t _{INHPLL}	0.0						ns			
tOUTCOPLL	0.5	2.1					ns			

Table 48. EP20K100C External Bidirectional Timing Parameters										
Symbol	-7 Spe	ed Grade	-8 Speed	Grade (2)	-9 Speed	-9 Speed Grade (2)				
	Min	Max	Min	Max	Min	Max				
t _{INSUBIDIR}	1.9						ns			
t _{INHBIDIR}	0.0						ns			
t _{OUTCOBIDIR}	2.0	5.0					ns			
t _{XZBIDIR}		7.1					ns			
t _{ZXBIDIR}		7.1					ns			
t _{INSUBIDIRPLL}	3.9						ns			
t _{INHBIDIRPLL}	0.0						ns			
†OUTCOBIDIRPLL	0.5	2.1					ns			
t _{XZBIDIRPLL}		4.2					ns			
t _{ZXBIDIRPLL}		4.2					ns			

Table 49. EP20K200C f _{MAX} LE Timing Parameters Note (1)										
Symbol	-7 Spee	d Grade	-8 Speed Grade (2) -9 Speed Grade (2)				Unit			
	Min	Max	Min	Max	Min	Max				
t_{SU}	0.3						ns			
t_H	0.3						ns			
t_{CO}		0.3					ns			
t _{LUT}		0.7					ns			

Table 60. EP20K400C External Bidirectional Timing Parameters										
Symbol	-7 Spe	ed Grade	-8 Speed	Grade (2)	-9 Speed Grade (2)		Unit			
	Min	Max	Min	Max	Min	Max	-			
t _{INSUBIDIR}	2.4						ns			
t _{INHBIDIR}	0.0						ns			
t _{OUTCOBIDIR}	2.0	5.0					ns			
t _{XZBIDIR}		7.1					ns			
t _{ZXBIDIR}		7.1					ns			
t _{INSUBIDIRPLL}	3.8						ns			
t _{INHBIDIRPLL}	0.0						ns			
t _{OUTCOBIDIRPLL}	0.5	2.1					ns			
t _{XZBIDIRPLL}		4.2					ns			
t _{ZXBIDIRPLL}		4.2					ns			

Table 61. EP20K600C f _{MAX} LE Timing Parameters Note (1)										
Symbol	-7 Spee	d Grade	-8 Speed	Grade (2)	-9 Speed	Grade (2)	Unit			
	Min	Max	Min	Max	Min	Max				
t_{SU}	0.3						ns			
t_H	0.3						ns			
t_{CO}		0.3					ns			
t _{LUT}		0.7					ns			

Table 62. EP20K600C f _{MAX} ESB Timing Parameters Note (1)									
Symbol	-7 Speed Grade		-8 Speed	Grade (2)	-9 Speed Grade (2)		Unit		
	Min	Max	Min	Max	Min	Max			
t _{ESBARC}		1.4					ns		
t _{ESBSRC}		2.5					ns		
t _{ESBAWC}		3.1					ns		
t _{ESBSWC}		3.0					ns		
t _{ESBWASU}	0.5						ns		
t _{ESBWAH}	0.5						ns		
t _{ESBWDSU}	0.6						ns		
t _{ESBWDH}	0.5						ns		
t _{ESBRASU}	1.4						ns		
t _{ESBRAH}	0.0						ns		
t _{ESBWESU}	2.3						ns		
t _{ESBDATASU}	0.0						ns		
t _{ESBWADDRSU}	0.2						ns		
t _{ESBRADDRSU}	0.2						ns		
t _{ESBDATACO1}		1.0					ns		
t _{ESBDATACO2}		2.3					ns		
t _{ESBDD}		2.7					ns		
t_{PD}		1.6					ns		
t _{PTERMSU}	1.0						ns		
t _{PTERMCO}		1.0					ns		

Table 63. EP20K600C f _{MAX} Routing Delays Note (1)										
Symbol	-7 Spee	d Grade	I Grade -8 Speed Grade (2)			-9 Speed Grade (2)				
	Min	Max	Min	Max	Min	Max				
t _{F1-4}	0.2						ns			
t _{F5-20}	0.9						ns			
t _{F20+}	2.2						ns			

Table 74. EP20K1500C f_{MAX} ESB Timing Parameters Note (1)									
Symbol	-7 Speed Grade		-8 Speed	Grade (2)	-9 Speed Grade (2)		Unit		
	Min	Max	Min	Max	Min	Max			
t _{ESBARC}		1.3					ns		
t _{ESBSRC}		2.3					ns		
t _{ESBAWC}		2.9					ns		
t _{ESBSWC}		2.7					ns		
t _{ESBWASU}	0.4						ns		
t _{ESBWAH}	0.4						ns		
t _{ESBWDSU}	0.6						ns		
t _{ESBWDH}	0.4						ns		
t _{ESBRASU}	1.3						ns		
t _{ESBRAH}	0.0						ns		
t _{ESBWESU}	2.0						ns		
t _{ESBDATASU}	0.0						ns		
t _{ESBWADDRSU}	0.1						ns		
t _{ESBRADDRSU}	0.1						ns		
t _{ESBDATACO1}		1.0					ns		
t _{ESBDATACO2}		2.0					ns		
t _{ESBDD}		2.4					ns		
t_{PD}		1.4					ns		
t _{PTERMSU}	0.9						ns		
t _{PTERMCO}		1.0					ns		

Table 75. EP20K15	OOC f _{MAX} Rou	ting Delays	Note (1)				
Symbol	-7 Spee	d Grade	-8 Speed	Grade (2)	-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
t _{F1-4}	0.2						ns
t _{F5-20}	1.4						ns
t _{F20+}	2.8						ns

Table 76. EP20K1500C Minimum Pulse Width Timing Parameters Note (1)										
Symbol	-7 Speed Grade		-8 Speed	Grade (2)	-9 Speed Grade (2)		Unit			
	Min	Max	Min	Max	Min	Max	-			
t _{CH}	2.0						ns			
t _{CL}	2.0						ns			
t _{CLRP}	0.2						ns			
t _{PREP}	0.2						ns			
t _{ESBCH}	2.0						ns			
t _{ESBCL}	2.0						ns			
t _{ESBWP}	1.0						ns			
t _{ESBRP}	0.8						ns			

Table 77. EP20K1500C External Timing Parameters										
Symbol	-7 Spee	ed Grade	-8 Speed	Grade (2)	-9 Speed	-9 Speed Grade (2)				
	Min	Max	Min	Max	Min	Max				
t _{INSU}	2.1						ns			
t _{INH}	0.0						ns			
t _{оитсо}	2.0	5.0					ns			
t _{INSUPLL}	3.2						ns			
t _{INHPLL}	0.0						ns			
t _{OUTCOPLL}	0.5	2.1					ns			

Power Consumption

To estimate device power consumption, use the interactive power estimator on the Altera web site at http://www.altera.com.

Configuration & Operation

The APEX 20KC architecture supports several configuration schemes. This section summarizes the device operating modes and available device configuration schemes.

Operating Modes

The APEX architecture uses SRAM configuration elements that require configuration data to be loaded each time the circuit powers up. The process of physically loading the SRAM data into the device is called configuration. During initialization, which occurs immediately after configuration, the device resets registers, enables I/O pins, and begins to operate as a logic device. The I/O pins are tri-stated during power-up, and before and during configuration. Together, the configuration and initialization processes are called *command mode*; normal device operation is called *user mode*.

Before and during device configuration, all I/O pins are pulled to V_{CCIO} by a built-in weak pull-up resistor.

SRAM configuration elements allow APEX 20KC devices to be reconfigured in-circuit by loading new configuration data into the device. Real-time reconfiguration is performed by forcing the device into command mode with a device pin, loading different configuration data, reinitializing the device, and resuming user-mode operation. In-field upgrades can be performed by distributing new configuration files.

Configuration Schemes

The configuration data for an APEX 20KC device can be loaded with one of five configuration schemes (see Table 81), chosen on the basis of the target application. An EPC16, EPC2, or EPC1 configuration device, intelligent controller, or the JTAG port can be used to control the configuration of an APEX 20KC device. When a configuration device is used, the system can configure automatically at system power-up.